

For Immediate Release

**TAIYO YUDEN Announces the Start of Development on Large-size Module Technology  
Based on its Embedded-Parts Multilayer Wiring Substrate “EOMIN™”**  
*A Significant Technological Advancement Dealing with the Mutual Interference in Circuits  
through Our Proprietary Shield Mold Technology*

Tokyo, September 8, 2014 - TAIYO YUDEN CO., LTD. announced today the development of large-size module technology using its copper-core embedded parts multilayer wiring substrate “EOMIN™”.

This innovation in module technology allows for hundreds of electronic components including devices for mobile communications (SAW filter/duplexer) to be embedded in the substrate, and at the same time, hundreds of components can be mounted on the substrate allowing the power supply circuits, high-frequency circuits, etc. to be mounted in a single package. With the use of TAIYO YUDEN’s proprietary shield mold technology, anti-noise measures can be taken for each functional block and the main functions necessary for smartphones and tablet devices can be integrated into a single module.

It is our full intention to extend the use of copper-core embedded parts multilayer wiring substrate “EOMIN™” to various applications and address critical market needs. Our product innovations in this area will continue to contribute to a reduction in size and thickness of devices through high-density packaging that involves the embedding of parts.

### **Technology Background**

Since the commercialization of the embedded parts multilayer wiring substrate “EOMIN™” in 2006, TAIYO YUDEN has been making continuous advancements in embedded parts technology by offering high-precision mounting of embedded parts, reduction in the size of via holes and copper wiring, and improvement in the reliability of copper plating.

Currently, through the integration of our technologies, we have developed basic capabilities for manufacturing large-size modules that enable embedding of hundreds of components, including devices for mobile communications (SAW filter/duplexer), in a substrate measuring 10cm<sup>2</sup>, in addition to the ability to mount hundreds of components on the substrate.

TAIYO YUDEN has combined its proprietary shield mold technology with noise resistance, which is a characteristic of “EOMIN™”. This allows for the prevention of noise interference in each circuit and the power supply circuits, high-frequency circuits, etc. can be mounted in a single module.

\*“EOMIN” is a registered trademark or trademark of TAIYO YUDEN CO., LTD. used both for Japan and other countries.